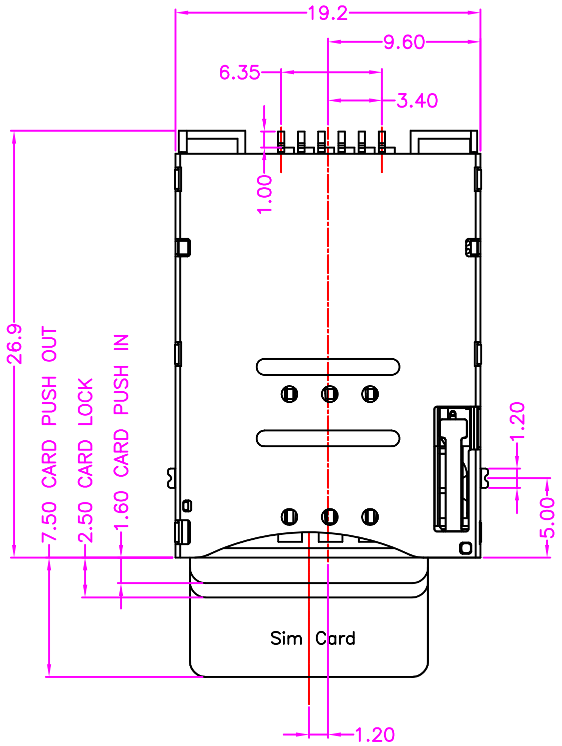
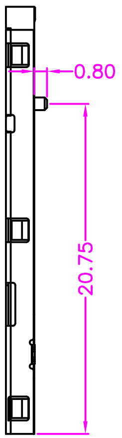
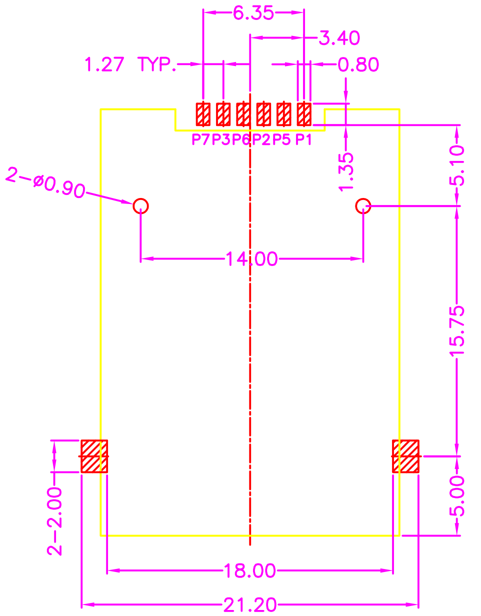
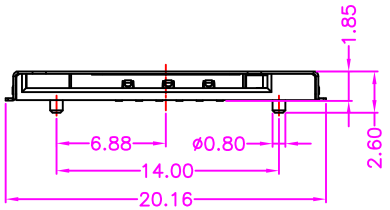


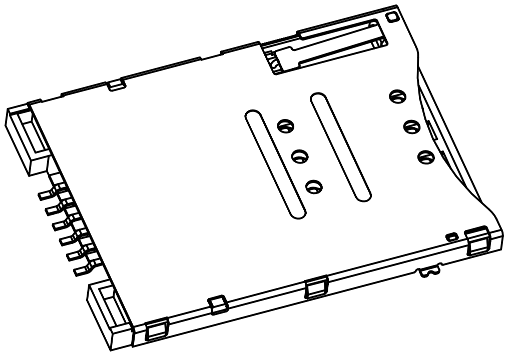




P.C.B LAYOUT
TOP VIEW ±0.05

▨ PAD AREA
☐ KEEP AREA





PART NUMBER:
4MCGD − 0 6 * T − 1 2 7

SERIES — 4MCGD
NO. OF POS. — 0 6
CONTACT PLATED OPTION — *
TIN PLATING ON SOLDER TAIL — T
TAPE REEL PACKAGE — 1 2 7

CONTACT PLATED OPTION
1: GOLD FLASH
3: 3u" GOLD
5: 5u" GOLD
7: 15u" GOLD
9: 30u" GOLD

MATERIALS
HOUSING: HI-TEMP. PLASTIC (UL 94V−0)
SHELL: STAINLESS STEEL, NICKEL PLATING
SOLDER PAD: STAINLESS STEEL, GOLD PLATING
TERMINAL: COPPER ALLOY, GOLD PLATED ON CONTACT AREA
TIN PLATING ON SOLDER TAIL

SPECIFICATION
CURRENT RATING: 0.5 AMP MAX
DIELECTRIC WITHSTANDING: 500V AC FOR ONE MINUTE
CONTACT RESISTANCE: 100m OHMS MAX
INSULATION RESISTANCE: 1000M OHMS MIN AT DC 500V
OPERATION TEMPERATURE: −40°C~+85°C

A	RELEASE	2015.8.19
REV.	DESCRIPTION	DATE

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TOLERANCES	TITLE	MEMORY CARD SERIES SIM CARD, 6PIN, PCB MOUNT, SMT, METAL SHIELD PUSH−PUSH TYPE, FEMALE				
X.X ±0.3 X.XX ±0.2 X.XXX±0.1 Angle ±5°	DRAWED BY		CHECKED BY		APPROVED BY	
	Tina		Lion		Benson	
	UNIT	SCALE	SIZE	DRAW NO.	REV.	Sheet
10140	MM	NONE	A4	4MCGD−008	A	1/1